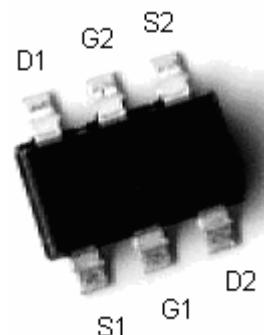


Dual P-Channel MOSFET

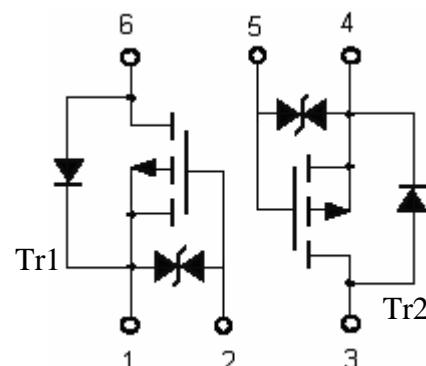
Features:

- Low on-resistance
- High ESD capability
- High speed switching
- Low-voltage drive(-2.5V)
- Pb-free package

SOT-363R



BVDSS	-50V
ID	-170mA
RDS(on)@VGS=-10V, ID=-100mA	5Ω (typ)
RDS(on)@VGS=-5V, ID=-100mA	6Ω (typ)
RDS(on)@VGS=-3V, ID=-30mA	8Ω (typ)



The following characteristics apply to both Tr1 and Tr2

Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Limits	Unit
Drain-Source Voltage	V _{DS}	-50	V
Gate-Source Voltage	V _{GS}	±20	
Continuous Drain Current @ T _A =25°C, V _{GS} =-5V (Note 3)	ID	-170	mA
Continuous Drain Current @ T _A =85°C, V _{GS} =-5V (Note 3)		-120	
Pulsed Drain Current (Notes 1, 2)	IDM	-800	mA
Maximum Power Dissipation (Note 3)	P _D	300	mW
		160	
Operating Junction and Storage Temperature	T _j , T _{stg}	-55~+150	°C

Note : 1. Pulse width limited by maximum junction temperature.

2. Pulse width≤ 300μs, duty cycle≤2%.

3. Surface mounted on 1 in²copper pad of FR-4 board, t≤5s.



Thermal Performance

Parameter	Symbol	Limit	Unit
Thermal Resistance, Junction-to-Ambient(PCB mounted) (Note)	R _{th,ja}	415	°C/W

Note : Surface mounted on 1 in²copper pad of FR-4 board, t≤5s.

Electrical Characteristics (T_j=25°C, unless otherwise noted)

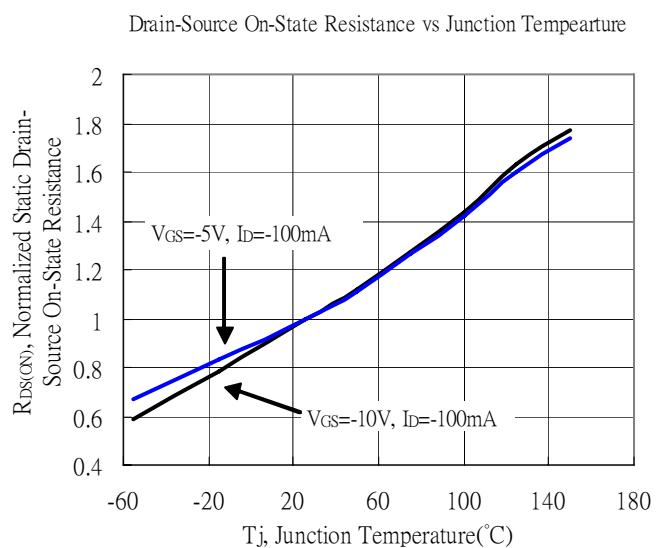
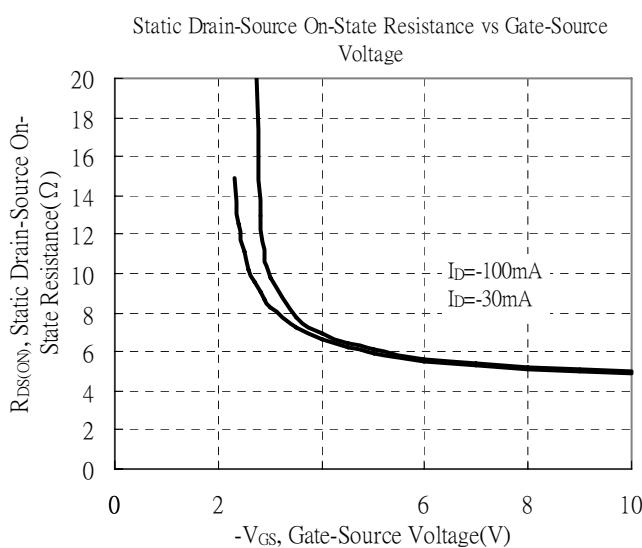
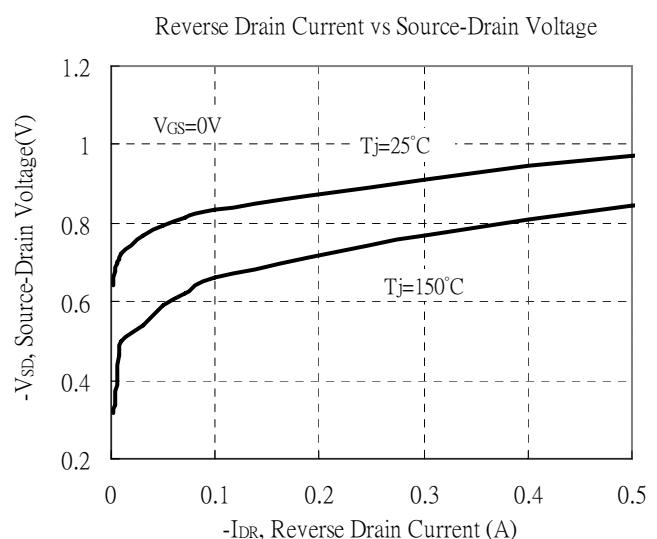
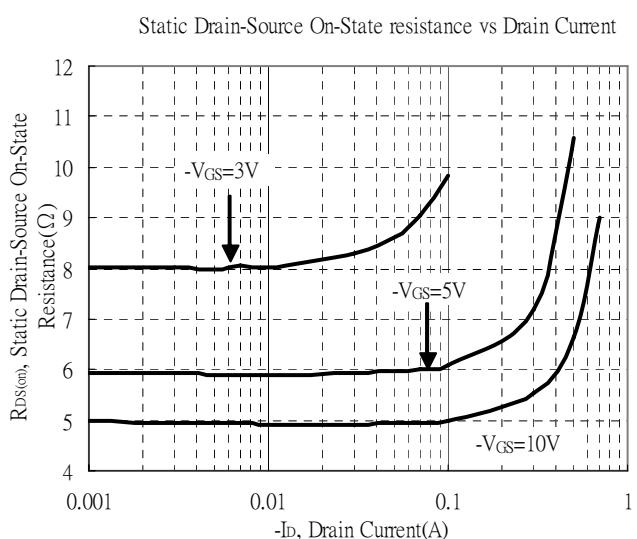
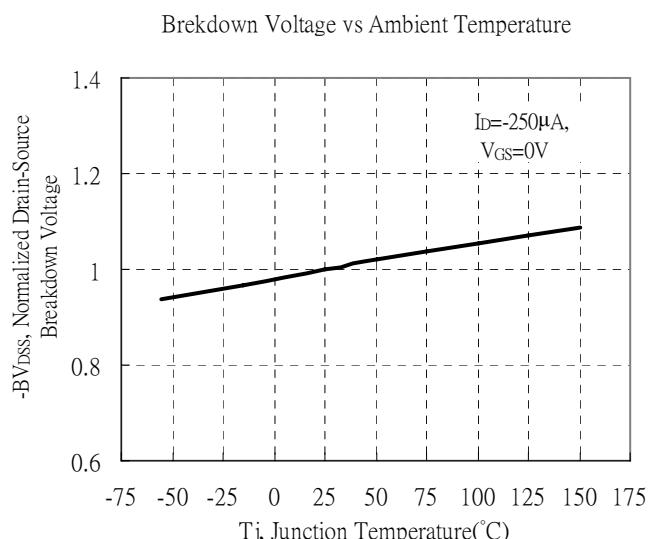
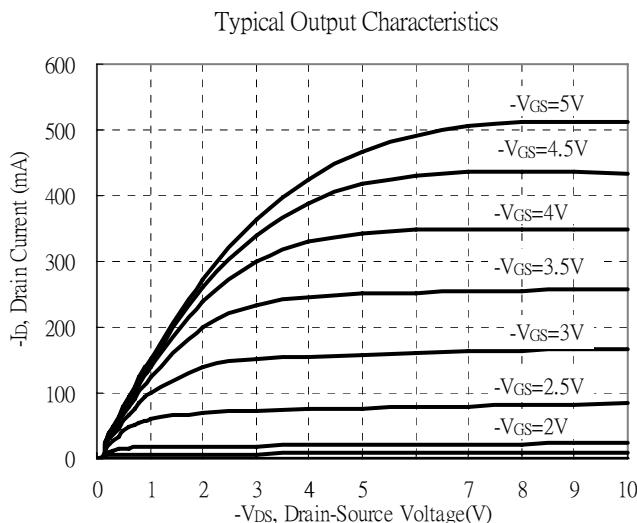
Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Static					
BV _{DSS}	-50	-	-	V	V _{GS} =0, I _D =-250μA
V _{GS(th)}	-1	-1.4	-2	V	V _{DS} =V _{GS} , I _D =-250μA
I _{GSS}	-	-	±8	μA	V _{GS} =±20V, V _{DS} =0
I _{DSS}	-	-	1		V _{DS} =50V, V _{GS} =0
	-	-	10		V _{DS} =40V, V _{GS} =0 (T _j =70°C)
*R _{DSON}	-	5	7	nA	V _{GS} =-10V, I _D =-100mA
	-	6	8.5		V _{GS} =-5V, I _D =-100mA
	-	8	12		V _{GS} =-3V, I _D =-30mA
*G _{FS}	80	-	-	mS	V _{DS} =-10V, I _D =-100mA
Dynamic					
C _{iss}	-	24	-	pF	V _{DS} =-25V, V _{GS} =0, f=1MHz
C _{oss}	-	4.6	-		
C _{rss}	-	1.5	-		
t _{d(ON)}	-	2.7	-	ns	V _{DS} =-25V, I _D =-100mA, V _{GS} =-5V, R _G =3.3Ω
t _r	-	3.3	-		
t _{d(OFF)}	-	7.4	-		
t _f	-	5	-	nC	V _{DS} =-40V, I _D =-170mA, V _{GS} =-5V
Q _g	-	1.4	-		
Q _{gs}	-	0.36	-		
Q _{gd}	-	0.29	-		
Source-Drain Diode					
*V _{SD}	-	-0.85	-1.2	V	V _{GS} =0V, I _S =-130mA

*Pulse Test : Pulse Width ≤300μs, Duty Cycle≤2%

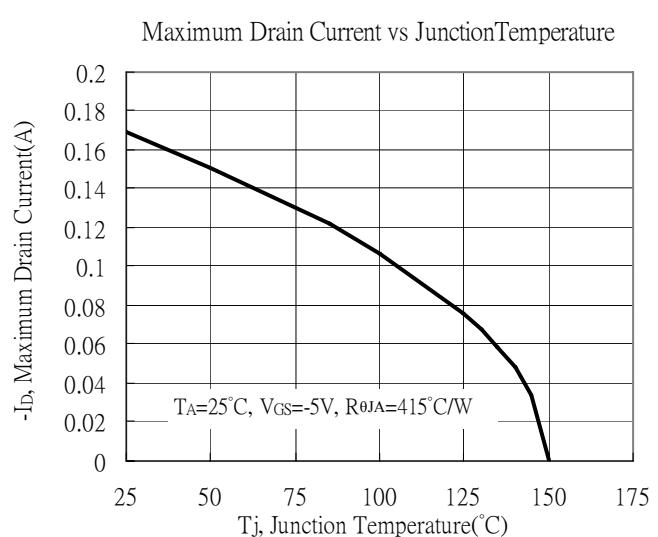
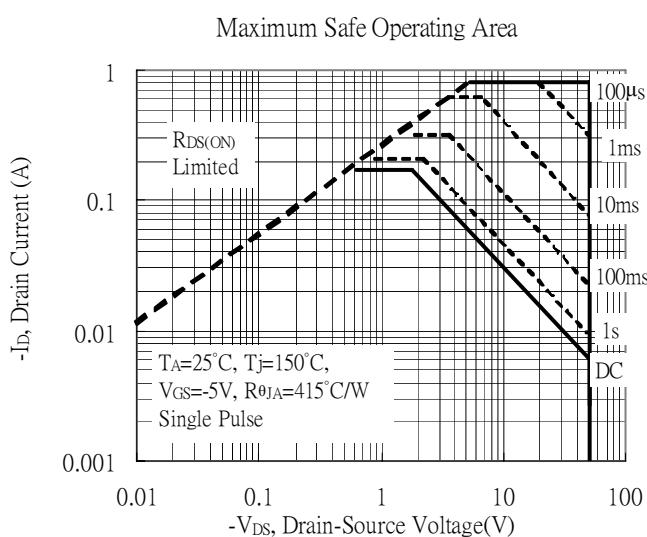
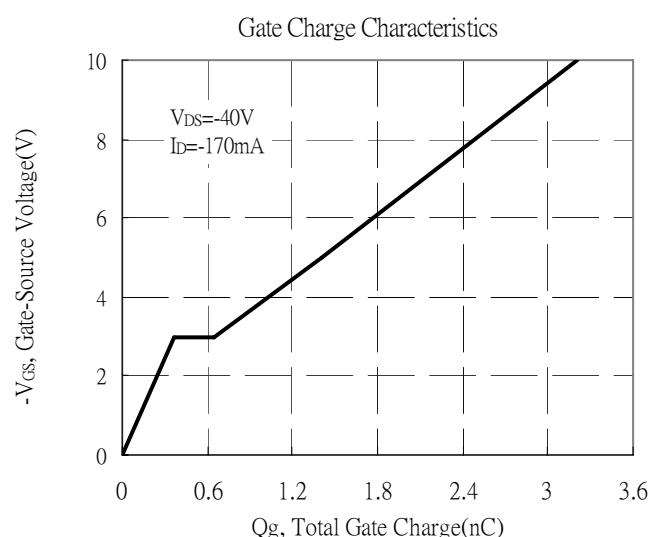
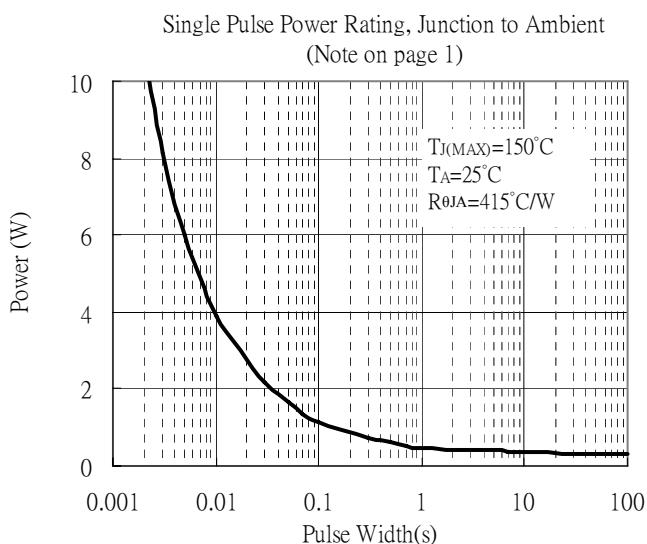
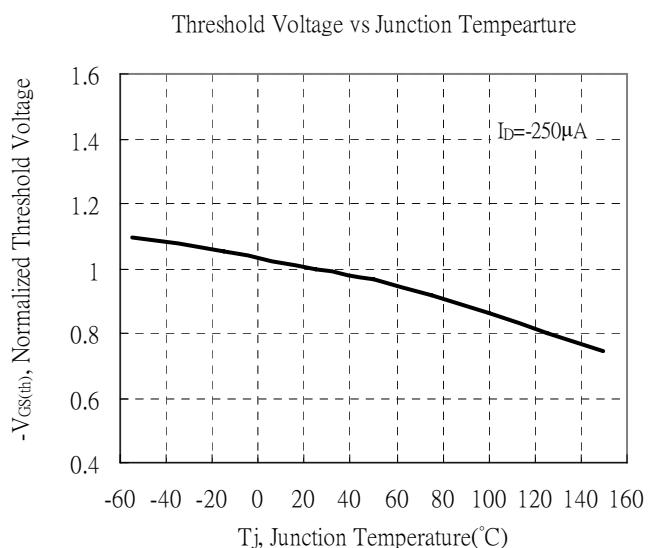
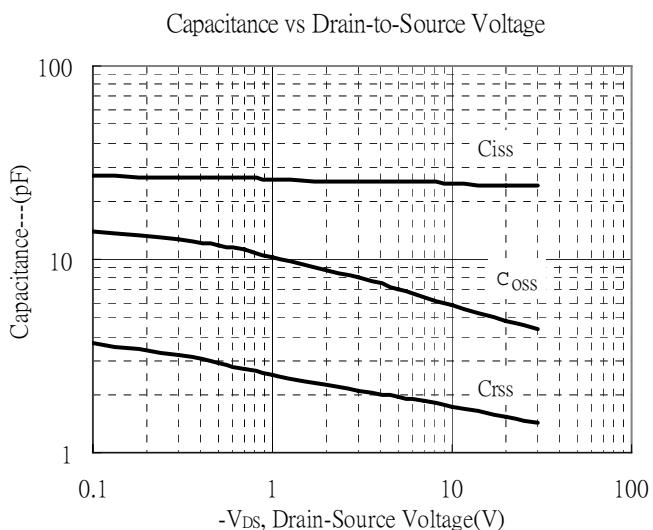
Ordering Information

Device	Package	Shipping
BSS84DW	SOT-363 (Pb-free lead plating and halogen-free package)	3000 pcs / Tape & Reel

Typical Characteristics

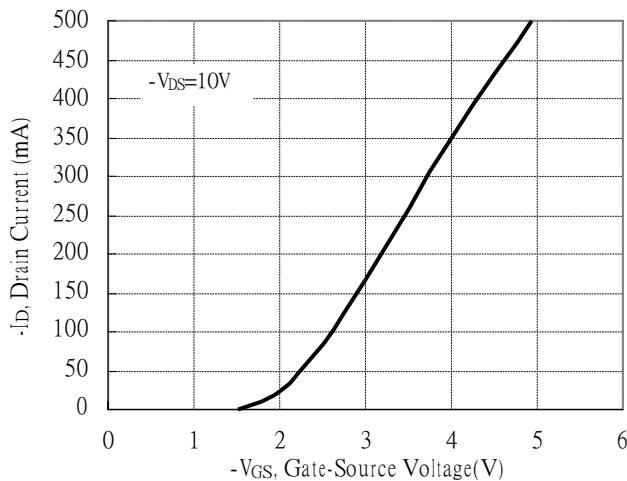


Typical Characteristics(Cont.)

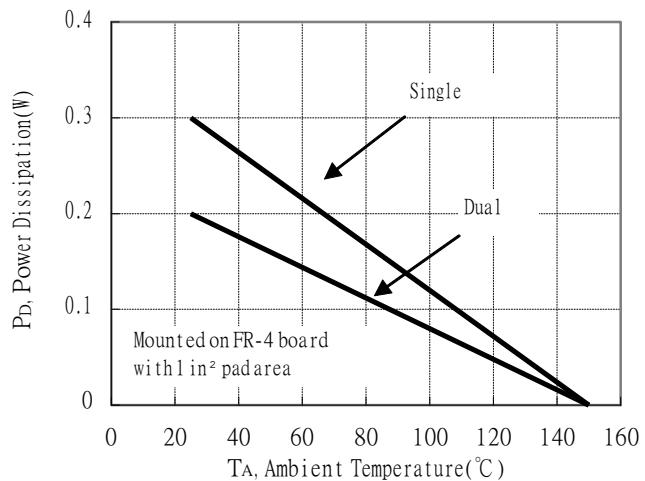


Typical Characteristics(Cont.)

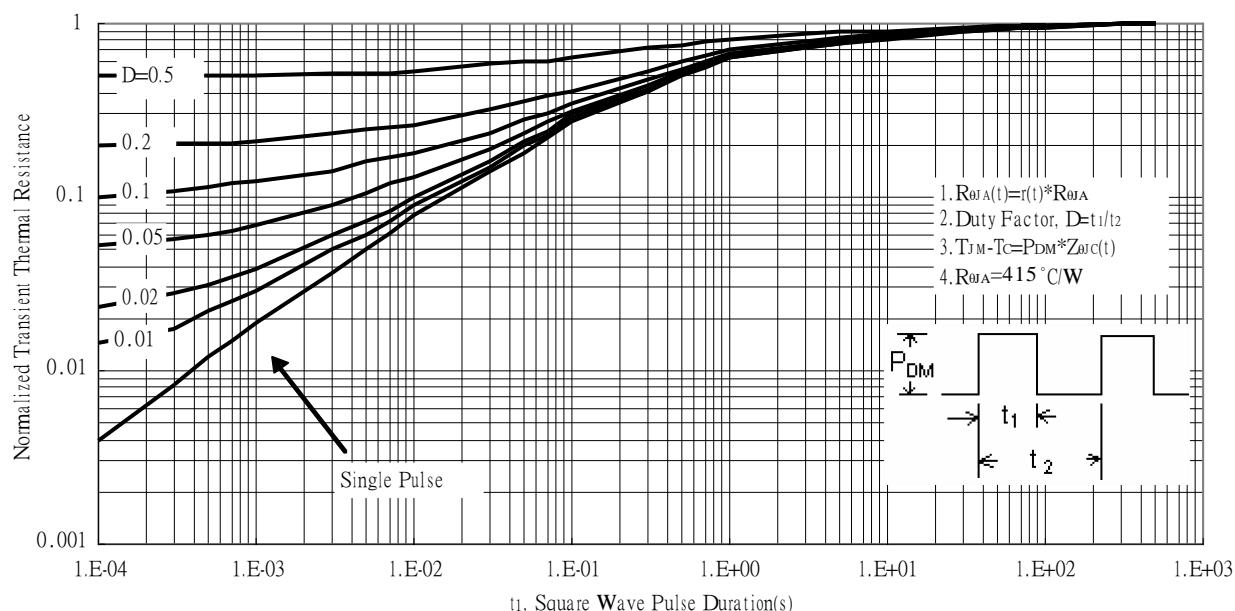
Typical Transfer Characteristics



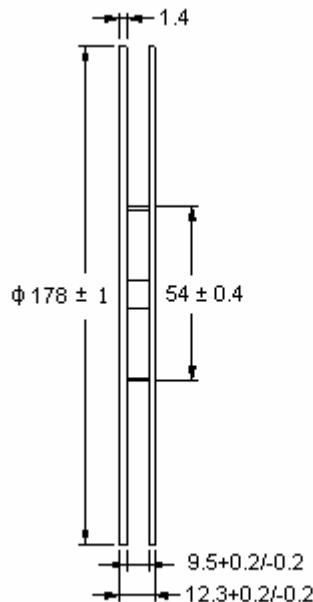
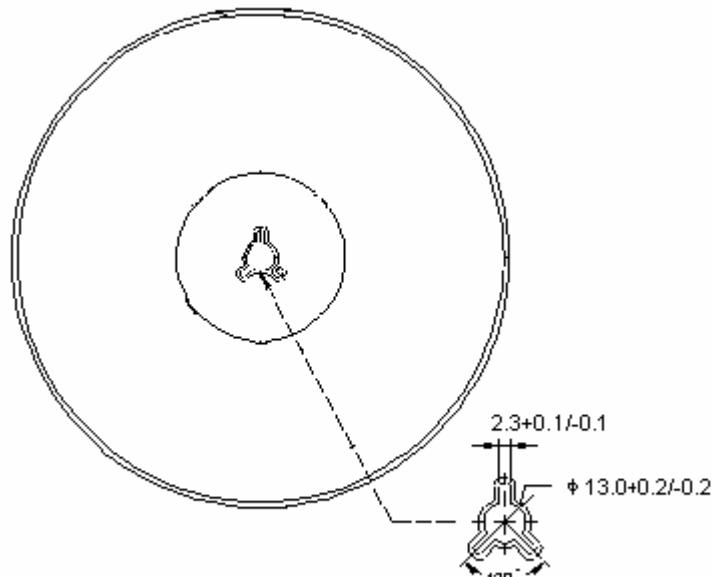
Power Derating Curves



Transient Thermal Response Curves

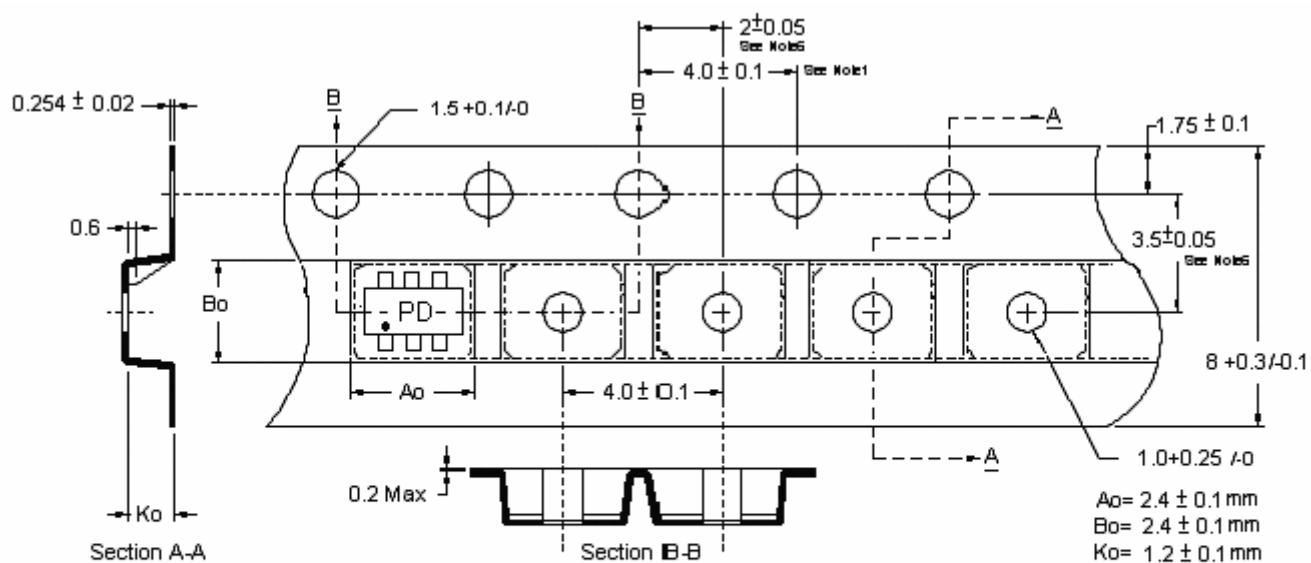


Reel Dimension



Unit: millimeter

Carrier Tape Dimension

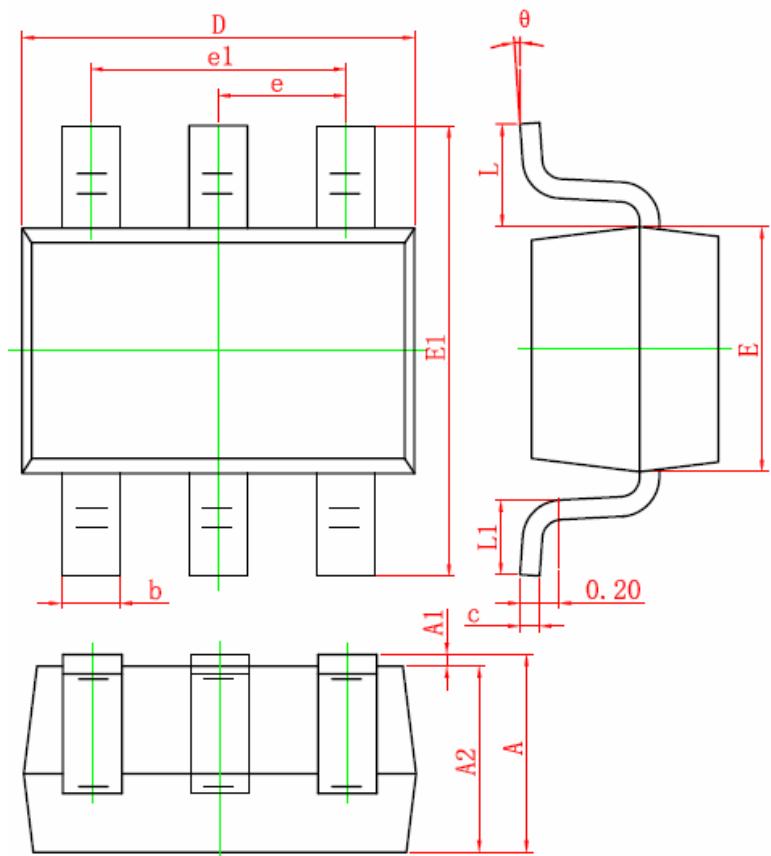


Notes:

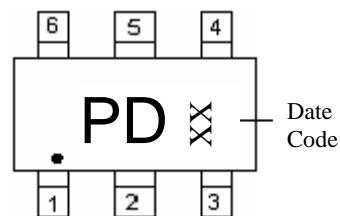
1. 10 sprocket hole pitch cumulative tolerance ± 0.2 .
2. Camber not to exceed 1mm in 100mm.
3. Material: Conductive Black Polystyrene.
4. A_0 & B_0 measured on a plane 0.3mm above the bottom of the pocket.
5. K_0 measured from a plane on the inside bottom of the pocket to the top surface of the carrier.
6. Pocket position relative to sprocket hole measured as true position of pocket, not pocket hole.

Unit : millimeter

SOT-363 Dimension



Marking:



6-Lead SOT-363R Plastic Surface Mounted Package

Style:

- Pin 1. Source1 (S1)
- Pin 2. Gate1 (G1)
- Pin 3. Drain2 (D2)
- Pin 4. Source2 (S2)
- Pin 5. Gate2 (G2)
- Pin 6. Drain1 (D1)

DIM	Millimeters		Inches		DIM	Millimeters		Inches	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.900	1.100	0.035	0.043	E1	2.150	2.450	0.085	0.096
A1	0.000	0.100	0.000	0.004	e	0.650	TYP	0.026	TYP
A2	0.900	1.000	0.035	0.039	e1	1.200	1.400	0.047	0.055
b	0.150	0.350	0.006	0.014	L	0.525	REF	0.021	REF
c	0.080	0.150	0.003	0.006	L1	0.260	0.460	0.010	0.018
D	2.000	2.200	0.079	0.087	θ	0°	8°	0°	8°
E	1.150	1.350	0.045	0.053					